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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





ZHX1810

***Slim Series SIR
Transceiver***

Product Specification

PS009320-0910



Warning: DO NOT USE IN LIFE SUPPORT

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Revision History

Each instance in the following table reflects a change to this document from its previous revision. To see more detail, click the appropriate link in the table.

Date	Revision Level	Description	Page #
September 2010	20	Updated Figure 9 and Figure 10. Deleted text about two different fab sources.	13, 14
June 2008	19	Removed Figure 8, Figure 9, Figure 13, and Figure 14 because Stars and Everlight supplied parts are obsolete.	

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Description

The ZILOG ZHX1810 is a low-profile version of Zilog's popular ZHX1010 1-meter transceiver. The transceiver is mechanically enhanced for ultra compact, power-conscious portable products, such as mobile phones, portable printers, handheld computers, and personal data assistants (PDAs). Designed to operate using the IrDA-Data mode, the transceiver combines an infrared emitting diode (IRED) emitter, a PIN photodiode detector, a digital AC coupled LED driver, and a receiver/decoder in a single package.

The ZILOG ZHX1810 provides an efficient implementation of the SIR standard in a small-outline footprint format. Application circuit space is also minimized, as only three components are required.

ZHX1810 also features an independently controlled shutdown that minimizes current draw to a maximum of 1 μ A.

Features

- Compliant to IrDA Data Specification SIR
- Wide power supply voltage range, 2.4 to 5.5 V
- Minimum link distance, 1 M
- Low-power, listening current, 90 μ A (typical) at 3.0 V
- Slim form factor (9.1 mm long x 3.8 mm wide x 2.73 mm high)
- Only two external components required
- Extended operating temperature range (-30 °C to $+85$ °C)
- Meets IEC 825-1 Class 1 Eye Safety Specifications

Block Diagram

Figure 1 is the block diagram for the Slim SIR transceiver.

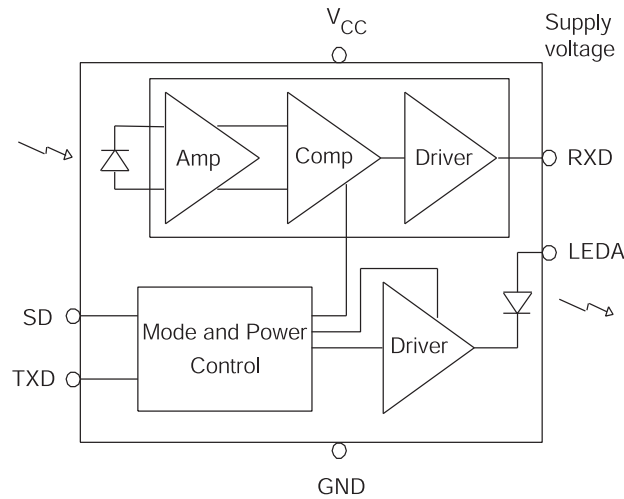


Figure 1. Slim SIR Transceiver Block Diagram

Pin Descriptions

The ZHX1810 transceiver uses the pins listed in Table 1. The pins are described in this section.

Table 1. Pin Out for the ZHX1810 Transceiver

Pin	Name	Function	I/O
1	LEDA	IRED anode	—
2	TXD	Transmitter input	I
3	RXD	Receiver output	O
4	SD	Enables shutdown mode	I
5	V _{CC}	Supply voltage	—
6	GND	Ground	—
—	TAB	Shield ground	—

LEDA LED Driver Anode

(Power)

This output is connected to the LED anode. Current to the LED is sourced through an external resistor.

TXD Transmit Data

(Input, active high)

This CMOS input is used to transmit serial data. This input has an internal pull-down resistor that is disabled (open-circuited) during shutdown.

RXD/Receive Data

(Output, active low)

This output indicates received serial data. It is a tri-state, slew rate controlled CMOS output (tri-stated during shutdown) driver capable of driving a standard CMOS load. No external resistor is required.

SD Shutdown

(Input, active high)

This input is used to place the integrated circuit into shutdown mode. Module shutdown current is influenced by the choice of capacitor used from V_{CC} to ground.

V_{CC} Positive Supply

(Power)

Connect to positive power supply (2.4–5.5 V). Filter with a 0.33- μ F ceramic bypass capacitor and terminating resistor as close as possible to the V_{CC} pin.

GND Ground

(Power)

Connect to ground of the power supply. A solid ground plane is recommended for proper operation.

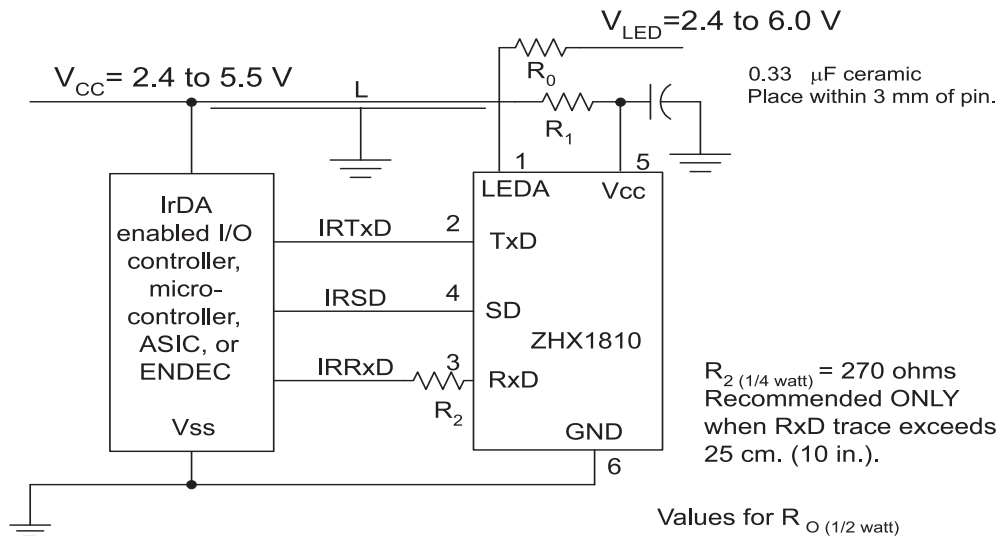
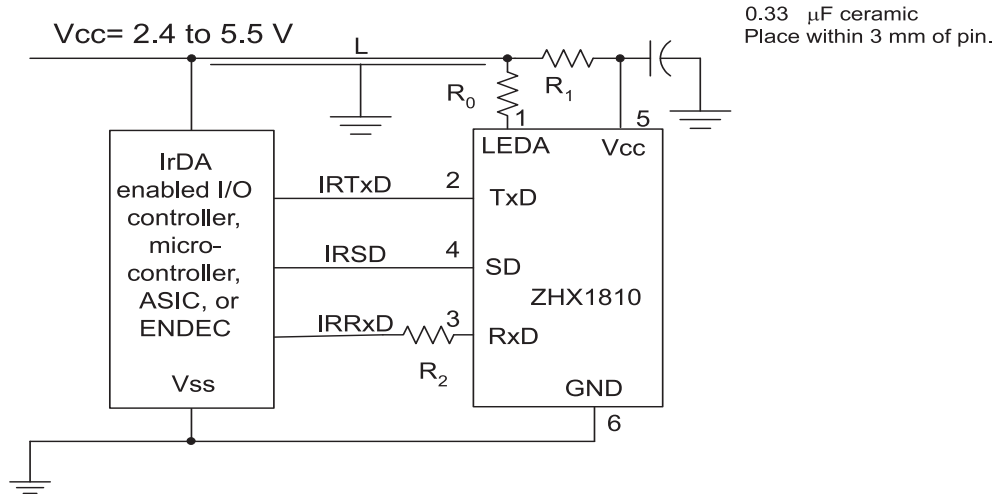
TAB

(Shield)

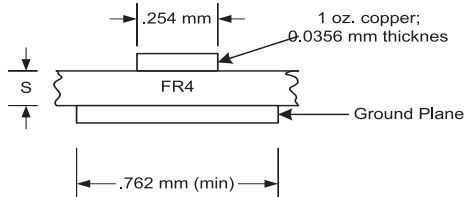
The Shield tab must be soldered to the ground plane.

Recommended Application Circuits

Figure 2 shows application block diagrams for the ZHX1810 transceiver.



Note: Lands to Pins 1, 2, 3, 4, and 5 should be 0.38 mm min. wide. Connect ground plane within 1.58 mm of pins.



Values for R_0 (1/2 watt)

V_{LED}	2.4	2.7	3.3	3.5	4	4.5	5	5.5	6	Volts
R_0	0.5	1.2	2.7	3.6	5.1	6.7	8.2	10.2	10.9	Ohms

Values for R_1 (1/4 watt)

S	.38 mm (.015")	.76 mm (.030")
R_1	68	91

Length, L, is not important.
Maintain land width constant without intermediate vias.
Make corners rounded not sharp.

Figure 2. Application Block Diagrams

Electrical and Timing Specifications

Table 2 through Table 4 present the electrical and timing specifications for the ZHX1810 transceiver.

Table 2. Absolute Maximum Ratings

Parameter	Symbol	Minimum	Maximum	Unit	Comment
Supply Voltage	V_{CC}	-0.3	6.0	V	V_{CC} , GND
Input Voltage	V_{IN}	GND-0.3	$V_{CC}+0.3$	V	TXD, SD
Output (External) Voltage	V_{OUT}	GND-0.3	$V_{CC}+0.3$	V	RxD
LED Current	I_{LED}		700	mA	20% duty cycle, $T_a=25\text{ }^\circ\text{C}$, $t_{ON}\leq 90\text{ }\mu\text{S}$
Storage Temperature	T_{ST}	-40	100	$^\circ\text{C}$	
Solder Temperature	T_{SOL}		240	$^\circ\text{C}$	
ESD			1,000	V	

Table 3. Recommended Operating Conditions

Parameter	Symbol	Minimum	Maximum	Unit
Supply Voltage	V_{CC}	2.4	5.5	V
LED Voltage	V_{LED}	2.4	6.0	V
Ambient Operating Temperature	T_{OP}	-30	85	$^\circ\text{C}$

Table 4. Electrical Characteristics

Parameter	Symbol	Condition	Min	Typical	Max	Unit	Remarks
High-Level Input Voltage	V_{IH}		$0.6 V_{CC}$		$V_{CC}+0.5$	V	TXD, SD
Low-Level Input Voltage	V_{IL}		-0.5		$0.2 V_{CC}$	V	TXD, SD
High-Level Output Voltage	V_{OH}		2.2			V	RxD
Low-Level Output Voltage	V_{OL}				0.4	V	RxD
Transmitter Current	I_{LED}			300		mA	
Listening Current	I_{CC}			90	150	μA	

Note: Unless otherwise noted: $V_{CC}=3.3\text{ V}$, GND= 0 V, $T_A=25\text{ }^\circ\text{C}$

Table 4. Electrical Characteristics (Continued)

Parameter	Symbol	Condition	Min	Typical	Max	Unit	Remarks
Receive Current	I_{CC}			90	150	μA	
Standby Current	I_{STB}				1	μA	SD= V_{CC} , TxD=0 V
Optical Rise/Fall Time	t_{Rr} , t_{Rf}			100		nS	
RxD Pulse Width	t_{PWA}	SIR=115.2 Kbps	1.1	1.6	3.9	μS	
Power Shutdown Time	T_{SD}				1	μS	
Startup Time	T_{STU}				200	μS	
Receiver Latency	T_L			100		μs	
Trans. Radiant Intensity	I_E	$I_{LED}=260$ mA	40		100	mW/sr	θ_h , $\theta_v \leq (\pm 15^\circ)$
Min. Threshold Irradiance	E_{emin}	$V_{CC}=3.3$ V		2	3	$\mu W/cm^2$	θ_h , $\theta_v \leq (\pm 15^\circ)$
Angle of Half Intensity	θ			20		$^\circ$	Hor. and Vert.
Light Pulse Rise, Fall Time	t_{or} , t_{of}			40		nS	
Optical Pulse Width	t_{OPW}			20		μS	TxD="H"
Optical Overshoot	t_{OPO}				3	%	
Peak Wavelength	λ_P			870		nm	
Note: Unless otherwise noted: $V_{CC}=3.3$ V, GND= 0 V, $T_A= 25$ °C							

Figure 3 through Figure 6 show various electrical characteristics.

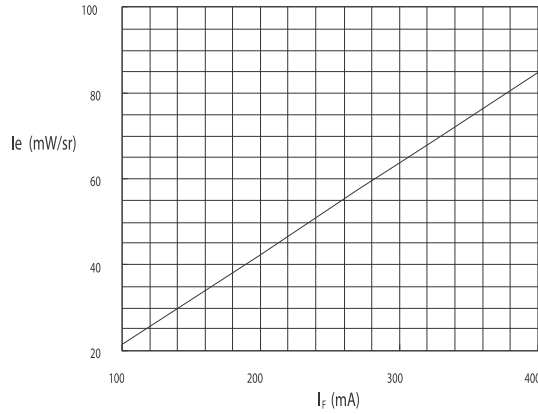


Figure 3. I_F-I_e Characteristics (0°)

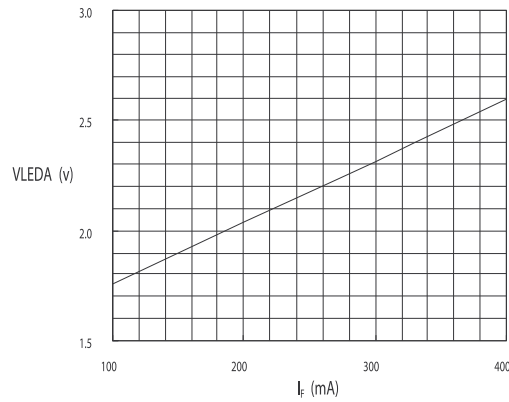


Figure 4. I_F-VLEDA Characteristics (0°)

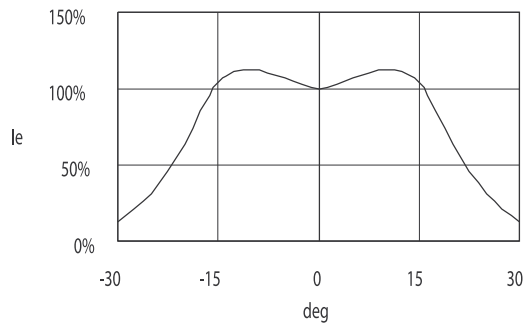


Figure 5. Directive Characteristics (Emitting)

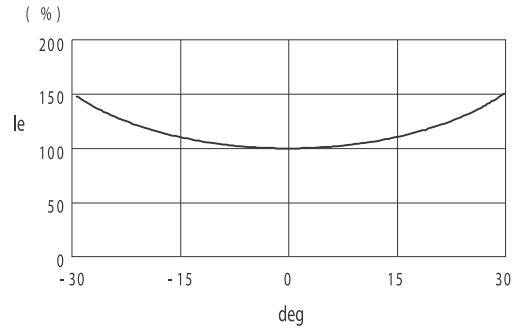
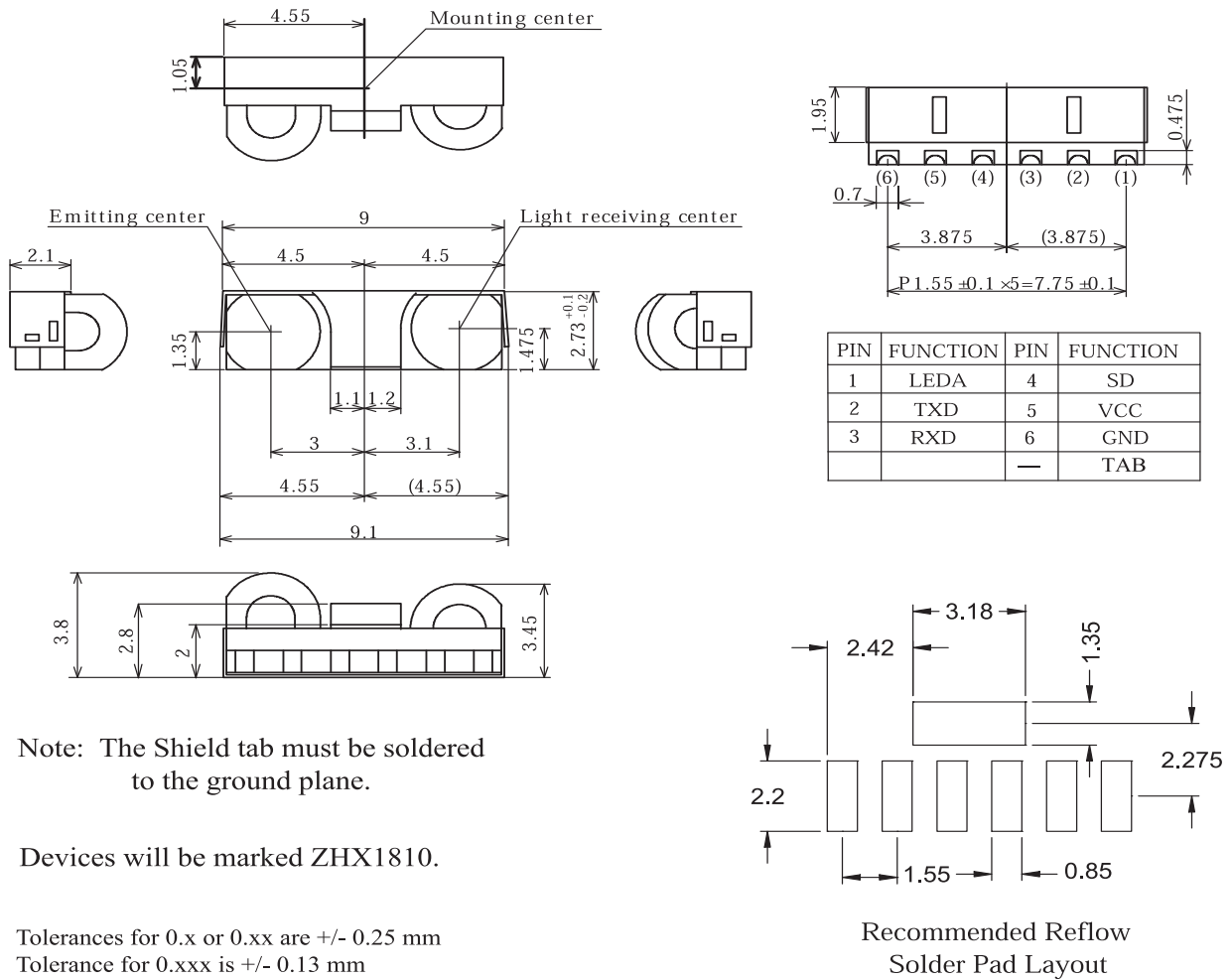


Figure 6. Directive Characteristics (Receiving)

Mechanical Drawings

The mechanical drawing for the transceiver is shown in Figure 7.



Note: The Shield tab must be soldered to the ground plane.

Devices will be marked ZHX1810.

Tolerances for 0.x or 0.xx are +/- 0.25 mm
Tolerance for 0.xxx is +/- 0.13 mm

Figure 7. ZHX1810 Mechanical Drawing

Soldering and Cleaning Recommendations

Follow these recommendations to maintain the performance of the ZHX1810 transceiver.

Reflow Soldering

- ▶ **Note:** Please refer to Zilog's Lead-Free Solder Reflow: Packaging Application Note (AN0161, <http://www.zilog.com/docstools.asp>) for more information about the solder profile.

Manual Soldering

- Use 63/37 or silver solder.
- Use a soldering iron of 25 W or smaller. Adjust the temperature of the soldering iron below 300 °C.
- Finish soldering within 3 seconds.
- Handle only after ZHX1810 has cooled off.

Cleaning (Preferred)

Perform cleaning after soldering under the following conditions:

- Cleaning agent: Alcohol
- Temperature and time: 30 seconds below 50 °C or 3 minutes below 30 °C
- Ultrasonic cleaning: Below 20 W

Additional cleaning methods can also be used. Please see the www.zilog.com documentation pages for details.

Packing, Storage, and Baking Recommendations

Follow these recommendations to maintain the performance of the ZHX1810 transceiver.

Storage

To avoid moisture absorption, ZHX1810 reels must remain in the original, unopened moisture-proof packing. Parts must be soldered within 72 hours after unpacking. Reels that have been unpacked, but will not be soldered within 72 hours, must be stored in a desiccator.

Baking

Parts that have been stored over 12 months or unpacked over 72 hours must be baked under the following guidelines.

Reels

60 °C for 48 hours or more

Loose Parts

- 100 °C for 4 hours or more
or
- 125 °C for 2 hours or more
or
- 150 °C for 1 hour or more

Moisture-Proof Packing

In order to avoid moisture absorption during transportation and storage, ZHX1810 reels are packed in aluminum envelopes (see Figure 8) that contain a desiccant with a humidity indicator. While this packaging is an impediment to moisture absorption, it is by no means absolute, and no warranty is implied. The user should store these parts in a controlled environment to prevent moisture entry. Please read the label on the aluminum bag for indicator instructions.

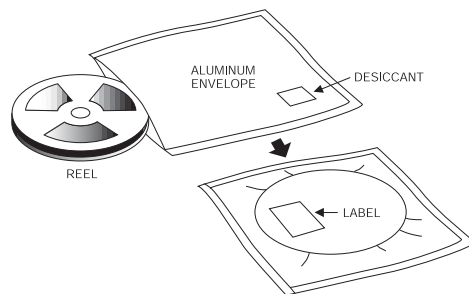
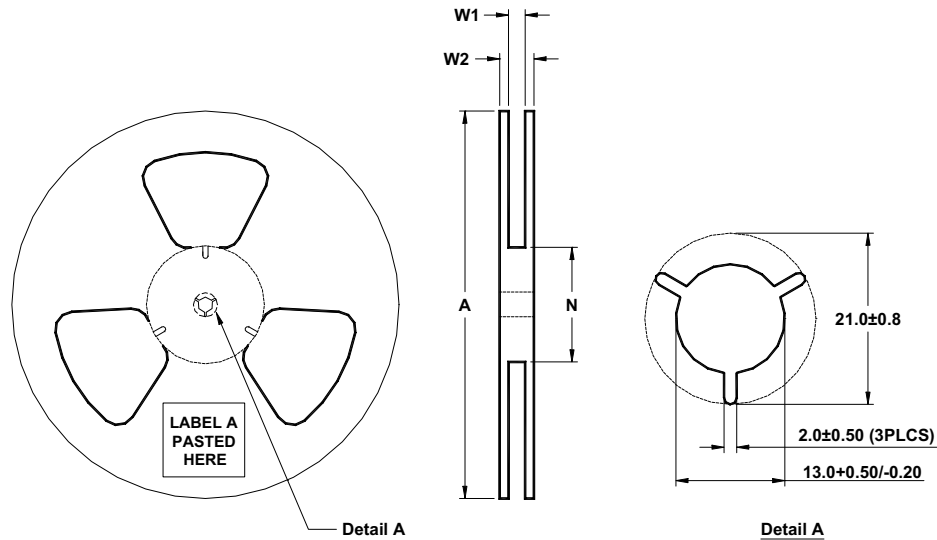


Figure 8. ZHX1810 Packaging

Taping Specifications

Figure 9 shows the reel dimensions for the ZHX1810. Figure 10 shows the tape dimensions and configuration for the ZHX1810.



- Note :
1. Material : Anti-Static Polyesterene.
 2. Surface Resistivity : $10E8$ to $10E10$ Ohms/SQ.
 3. Unless specified, Tol : ± 0.1

DEVICE	Carrier Tape Size	A	W1	W2 (max)	N (Hub Dia.)	Reel Qty
		± 0.25	$+2/-0$			
ZHX1810	16 mm	330	16.4	21.6	80 mm	2,000

Figure 9. ZHX1810 Reel Dimensions (Unit: mm)

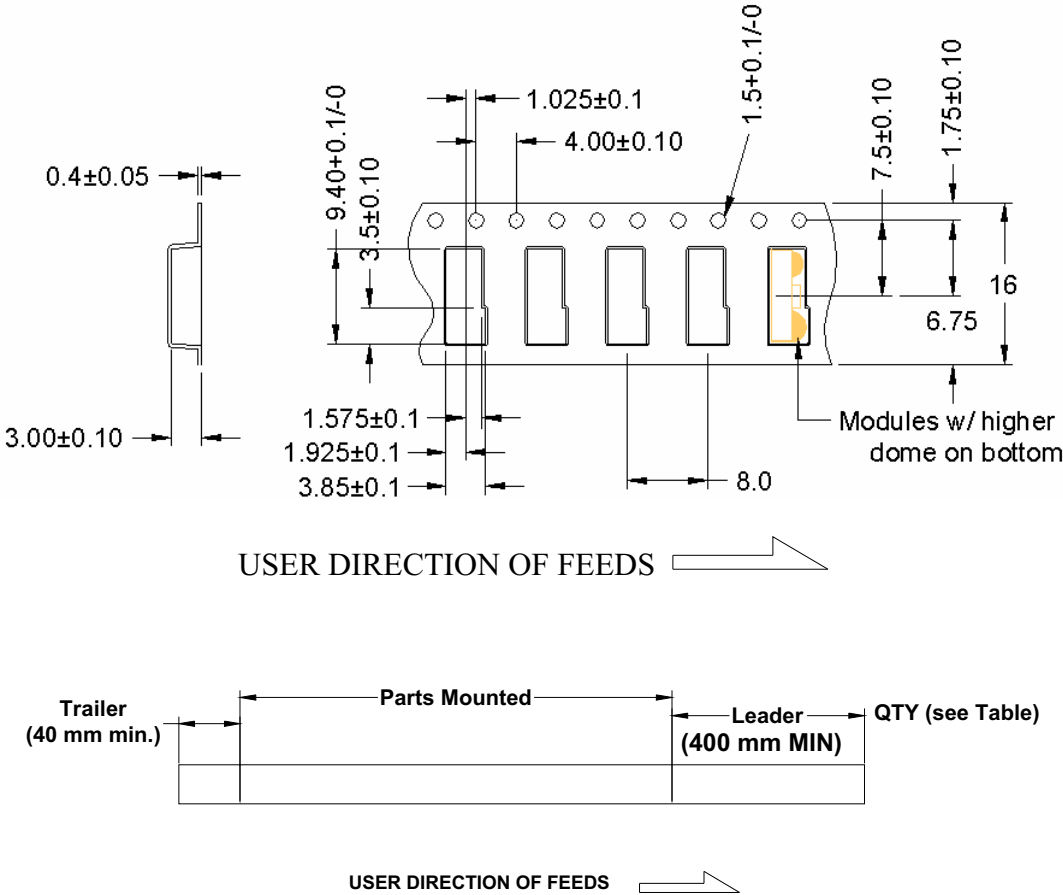


Figure 10. ZHX1810 Tape Dimensions and Configuration (Unit: mm)

Ordering Information

To order ZHX1810, use Zilog part number ZHX1810MV115THTR.

- ▶ **Notes:** All Zilog devices are available lead free. Since 2005, ZHX1810 has been manufactured with lead-free components. When ordering from your Zilog distributor, there is a possibility that the parts containing lead might be shipped. To ensure that you receive lead-free devices, please use part number ZHX1810MV115TH2090TR. These devices meet or exceed RoHS Directive 2002/95/EC. For additional information, please see the Zilog Quality and Reliability web page at <http://www.zilog.com/quality/index.asp>.

Customer Support

For answers to technical questions about the product, documentation, or any other issues with Zilog's offerings, please visit Zilog's Knowledge Base at <http://www.zilog.com/kb>.

For any comments, detail technical questions, or reporting problems, please visit Zilog's Technical Support at <http://support.zilog.com>.